



1714

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING
DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS
FIRST-CLASS MAIL IN AN ENVELOPE ADDRESSED TO:
ASSISTANT COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231
ON THIS 1ST DAY OF OCTOBER, 2001.

BY Richard M. BachA
#4/jm
10.11.01

1998/G 004 (5587*264)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

STEFAN DISCH ET AL

SERIAL NO: 09/647,743

ART UNIT: 1714

FILED: OCTOBER 4, 2000

EXAMINER: HOKE, V.

FOR: POLYOXYMETHYLENE MOULDING
MATERIAL WITH IMPROVED
PROCESSING STABILITY AND A
REDUCED EMISSIONS TENDENCYAssistant Commissioner for Patents
Washington, DC 20231

RECEIVED
OCT 09 2001
TC 1700

Sir:

In response to the outstanding Office Action dated July 2, 2001, kindly amend the above identified application as follows.

IN THE CLAIMS

Cancel claims 2, 3, and 5-10.

Amend claims 1 and 4 as follows.

A1

1. A molding composition made from linear polyoxymethylene copolymers which essentially have oxymethylene units and oxyethylene units as structural units in the polymer chain, where the proportion of oxyethylene units in the structural units of the polymer chain is from 1.5 to 2.5 mol%, the molding composition having a formaldehyde emission, measured on sheets of wall thickness 1 mm after 24 hours in storage, in